

Connecting Devices to the Internet of Things

SITUATION

At the heart of the IoT are complex, connected and modularized products that require a significant increase in the number of internal systems that will drive the use of multiple printed circuit board (PCB) and flex assemblies. Those assemblies demand connectors with improved signal integrity for speed, a profile designed for space-savings and superior robustness in tight spaces.

Do you know enough about the latest IoT-enabled interconnectors to address these challenges?



- The inside profile of IoT applications is becoming more space constrained. Increased modularity limits the space for the connector and other components, requiring more profile and orientation micro connector options.
- Having multiple profile and orientation micro connector options gives designers flexibility to address space, location and connector entry point challenges.

molex

WHAT'S TRENDING

The Right Connector for Seamless IoT Integration

5G wireless network technology will drive more of everything. More smart devices. More communication between those devices. More data and decisions based on that data.

5G will also influence how we work and how we live. Even something as simple as a toothbrush is part of this technology revolution, evolving from its humble origins of bone and hog's hair to a device so smart it can tell if you're vitamin deficient — and then order those vitamins for next-day delivery.

Smart toothbrushes are just one example of the millions of devices that will require modularity — active chips, memory modules and connection points. These dense and complex new applications will require exceptional signal integrity built into the board-to-board and flex-to-PCB connection points to accommodate higher speeds at an ultra-low-profile setting.

And it will require a partner that understands connectors — products tested in established consumer and industrial markets, with a proven track record for performance and the ability to handle the thousands of devices that will connect simultaneously.

Molex has the engineering resources and industry experts on the front lines of IoT development to help you capture and process data so every activity is more productive. Learn more about preparing for 5G technology.



- [**Pico-Lock B-to-B Connectors**](#)
- [**Micro-Lock Plus W-to-B Connectors**](#)
- [**Power B-to-B Connectors**](#)
- [**SlimStack FSB5 Floating Connectors**](#)
- [**Easy-On FPC Connectors**](#)

SOLUTION:

Pico-Lock Wire-to-Board Connectors

- Side positive locking system for high retention force and max space savings
- Ultra-low-profile right-angle design
- Up to 3.5A per circuit design



SOLUTION:

Micro-Lock Plus Wire-to-Board Connectors

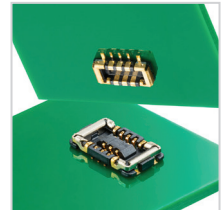
- Design flexibility with multiple pitches, mating orientations, dual-and single-row options
- Robust low-profile mechanical locking system for optimal retention force



SOLUTION:

Power Board-to-Board Connectors

- 3.0 to 10.0A of current capabilities
- Dual contact terminal design for signal assurance in high-shock and vibration environments
- Wrap-around nail design for additional mechanical robustness



SOLUTION:

SlimStack FSB5 Floating 0.4mm-Pitch Board-to-Board Connectors

- +/- 0.5mm of floating range in any direction for ease of mating and superior performance in high shock and vibration environments
- 125°C operating temperature
- High speed supports up to 6 Gbps
- Offered in multiple mating heights



SOLUTION:

Easy-On 0.5mm-Pitch FPC Connectors

- Orientation options – vertical and right angle
- Large range of actuator styles for design flexibility and robustness
- Multiple profile option for maximum space savings
- 105°C operating temperature



molex